

## Electro-Science Laboratories, Inc.

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**590** 590-G

## **CERMET SILVER CONDUCTOR**

ESL 590 and ESL 590-G conductive pastes offer versatility and superior performance in many applications. These low cost compositions may be selected for applications requiring shielding, solder seal metallization for axial components, and conductive wiring. With their versatility, 590 and 590-G can also be used in AC and DC plasma displays, and as terminations for monolithic capacitors and capacitor electrodes. Both 590 and 590-G exhibit excellent adhesion, high conductivity and electroplatability. They also feature very low firing temperature characteristics.

Suitable substrates include silicon wafers, various ceramics, porcelain enameled steel, soda-lime and other glass substrates. These conductive coatings are compatible with various glossy and matte finish dielectrics.

## **PASTE DATA**

RHEOLOGY: Thixotropic, screen printable paste

VISCOSITY:

(Brookfield RVT, ABZ Spindle, 10 rpm, 25.5°C±0.5°C) 590 250±25 Pa·s

> 225±25 Pa·s 590-G

**BONDING MECHANISM:** Fritted

SHELF LIFE: (25°C) 6 months

## **PROCESSING**

SCREEN MESH/EMULSION:  $325/25 \mu m$ **LEVELING TIME:** (25°C) 5-10 minutes DRYING AT 125°C: 10-15 minutes

590/G 9808-F

FIRING RANGE: 590 500°C-700°C

**590-G** 450°C-580°C

OPTIMUM PEAK TEMPERATURE/TIME AT PEAK: 590 580°C/10-15 min.

**590-G** 450°C/35 min.

**RATE OF ASCENT/DESCENT:** 60°C-100°C/minute

SUBSTRATE OF CALIBRATION: glass

THINNER: ESL 401 or 404

**TYPICAL PROPERTIES** 

**FIRED THICKNESS**: 590 12.5±2.5 μm

**590-G** 12.0±3.0 μm

**RESISTIVITY:** 3-5 m $\Omega$ /sq.

**PRINTING RESOLUTION:** 

(Line/Space) 125 μm x 125 μm

**SOLDER WETTABILITY:** 

(RMA flux, 5 sec. dip) 62 Sn/36 Pb/2 Ag, 220°C±5°C good-excellent

**ADHESION:** 

(90° pull, 2.5 mm x 2.5 mm pads, 62 Sn/36 Pb/2 Ag)

Initial pull strength:  $10\pm0.5 \text{ N}$